

ABSTRACT

A polishing pad for chemical mechanical polishing comprises a polishing layer and a subpad. The polishing layer has a polishing surface and a polishing layer interface surface opposite the polishing surface and comprises a polishing material. The subpad layer has a subpad interface surface adjacent to the polishing layer interface surface and a bottom surface opposite the subpad interface surface, and comprises a subpad material. The subpad layer has an average elastic modulus under compression at pressures of from 24 to less than 48 kPa of 1 to 5 MPa and an average elastic modulus under compression at pressures of 48 to 76 kPa of 5 to 20 MPa and a true strain of less than or equal to 10% over compression pressures of up to 1.2 MPa.

Fig. 4